

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.47566	100.0	1.1
Subtotal				0.47566	100	1.1
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.59114	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
Subtotal				1.5913	100	3.68
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01199	0.03	0.02772
	Copper alloy	Iron (Fe)	7439-89-6	0.03995	0.1	0.09239
	Copper alloy	Copper (Cu)	7440-50-8	39.79135	99.6	92.02044
	Pure metal layer	Silver (Ag)	7440-22-4	0.10787	0.27	0.24945
Subtotal				39.95116	100	92.39
Adhesive	Polymer	Paraffin wax	8002-74-2	0.18508	20.0	0.428
	Polymer	Epoxy resin system		0.07403	8.0	0.1712
	Filler	Silver (Ag)	7440-22-4	0.66627	72.0	1.5408
Subtotal				0.92538	100	2.14
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.42395	2.5	3.293
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.27186	7.5	9.879
	Filler	Silica -amorphous-	7631-86-9	21.07453	37.0	48.7364
	Pigment	Carbon black	1333-86-4	0.28479	0.5	0.6586
	Polymer	Epoxy resin system		8.54373	15.0	19.758
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.07453	37.0	48.7364
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28479	0.5	0.6586
Subtotal				56.95818	100	131.72
Wire	Pure metal	Gold (Au)	7440-57-5	0.09833	100.0	0.2274
Subtotal				0.09833	100	0.2274
Total				100.00001	100	231.2574

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.